

B1
Plastic

IN THE SPECIFICATION:

Please replace the paragraph on page 10, lines 6-10 with the following rewritten paragraph.

The individual layer blank 110 shown in Fig. 2 and formed from such a formation tool already has, for instance, conductor trench preforms 112, a mount preform 114 as well as *BC* positioning formation preforms generally shown at 116, here embodied as depressions 116B and/or protrusions 116A. A cooling groove preform 120 is also provided, the function of which will be described later.

Please replace the paragraph on page 12, lines 13-21 with the following rewritten paragraph.

B3 In Fig. 6 there is shown an embodiment of a circuit board which consists of two superimposed individual layers. The two individual layers are positioned by an engagement of the protrusions 16A which are formed on the upper side of the lower individual layer, in the depressions 16B which are formed on the underside of the upper individual layer. In this way there can be arranged, of course, more than two individual layers on top of each other, so that a circuit board is formed which consists of a plurality of individual layers. Only for reasons of better clarity the embodiments described have two individual layers each.

Please replace the paragraph on page 12, lines 27-30 through page 13, lines 1-7 with the

following rewritten paragraph.

In order to make possible an electrical bonding between various functional sides of the individual layers, the individual layers 10 in the embodiment shown in Fig. 6 are provided with a through hole 22 each, which is already formed in the individual layer blank 110 as a through hole preform 122. The through hole preform 122, too, is metallized during the pre-metallization and subsequent galvanic thickening, so that an electrical conductive connection is achieved between the two functional sides of the individual layer 10. On mounting the individual layers to each other an electrical conductive adhesive 24 is used in the region of the through hole 22, so that the desired electrical connection is achieved by conductive bonding. As an alternative, a soldering paste could be used.

Please replace the paragraph on page 13, lines 8-12 with the following rewritten paragraph.

According to a further development (not shown) the through hole 22 could also be designed to have such a diameter and the metallization deposited there could be configured to have such a wall thickness, that similar to the effect of the cooling groove, a heat removal is possible by thermal conduction between the two functional sides of an individual layer.

Please replace the paragraph on page 14, lines 6-13 with the following rewritten paragraph.

In Fig. 8 there is illustrated an embodiment in which a cooling channel 34 is provided on the upper side of the lower individual layer, which cooling channel may be used for active